



Product Change Notification

Change Notification #: 118764-01
Change Title: Microprocessor land-grid array (LGA) products sold in trays
PCN 118764-01, Transport Media, Adding a moisture-barrier bag, 2 desiccant pouches, and a humidity-indicator card
Reason for Revision: Share with Customers three different package configurations for LGA Shipments they could receive

Date of Publication: June 21, 2022

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	May 09, 2022
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Description of Change to the Customer:

Reason for Revision: Share with Customers the 3 different package configurations for LGA Shipments they could be receive

Intel is changing the packaging materials for Intel microprocessor land-grid array (LGA) products sold in trays. This change will not affect packaging for products sold in retail boxes. Intel will package these LGA microprocessors in a moisture-barrier bag (MBB) sealed with two desiccant pouches and a humidity-indicator card (HIC). Standard Intel product-and-handling labels will be affixed to the outside of the MBB.

PICTORAL EXAMPLES

Current Tray Packaging Configuration
(No MBB, desiccant pouches, or HIC)



New Tray Packaging Configuration
(with MBB, desiccant pouches, and HIC)



Standard Intermediate Box (I-box) Label will be placed on the MBB.	Standard MBB Handling Label will be placed on MBB.

Note: All images above are for example only. Any custom-specific labels will be placed on the MBB in like manner.

Customer Impact of Change and Recommended Action:

Migration to the new packaging will start May 9, 2022, and continue through the end of 2022. During that time, customers may receive LGA microprocessors in both the old and new packaging.

As Intel implements the MBB packaging globally in its factories through 2022, each factory's process varies, which may result in three packaging configurations. Customers may receive:

- material not in an MBB with a bag-seal date on the label
- material not in an MBB without a bag-seal date on the label
- material in an MBB with a bag-seal date on the label (packaging fully implemented)

The different packaging configurations result from factories implementing the MBB packaging at different times, while the change in labeling is happening at the same time globally. Each configuration is anticipated and a normal part of our phased approach. Please consult your Intel representative as needed.

Customers may need to make changes to their processes, such as removing the LGA microprocessors from the MBB and disposing of MBBs, the HICs, and the desiccant pouches. This change does not affect product shelf life or moisture-sensitivity level. Nor does the change require the products to be re-qualified or re-certified.

Intel is making this packaging change to reduce product exposure to things such as water, ambient moisture, or contaminants during shipment and storage. Such exposure could lead to the discoloration of the product or other undesired effects. This packaging change will enhance product-quality control after manufacturing and help customers limit the products' exposure to environmental factors.

Please contact your local Intel representative for any questions or concerns regarding the change communicated within this Product Change Notification.

Products Affected/Intel Ordering Codes:

Please see the attached Excel spreadsheet with the list of affected products.

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 04, 2022	00	Originally Published PCN
June 21, 2022	01	Share with Customers three different package configurations for LGA Shipments they could receive



Product Change Notification

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

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